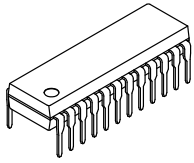


MECHANICAL CASE OUTLINE

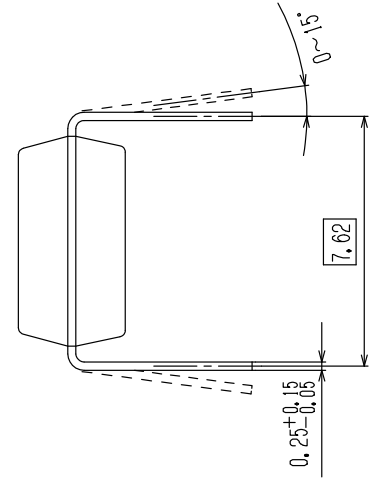
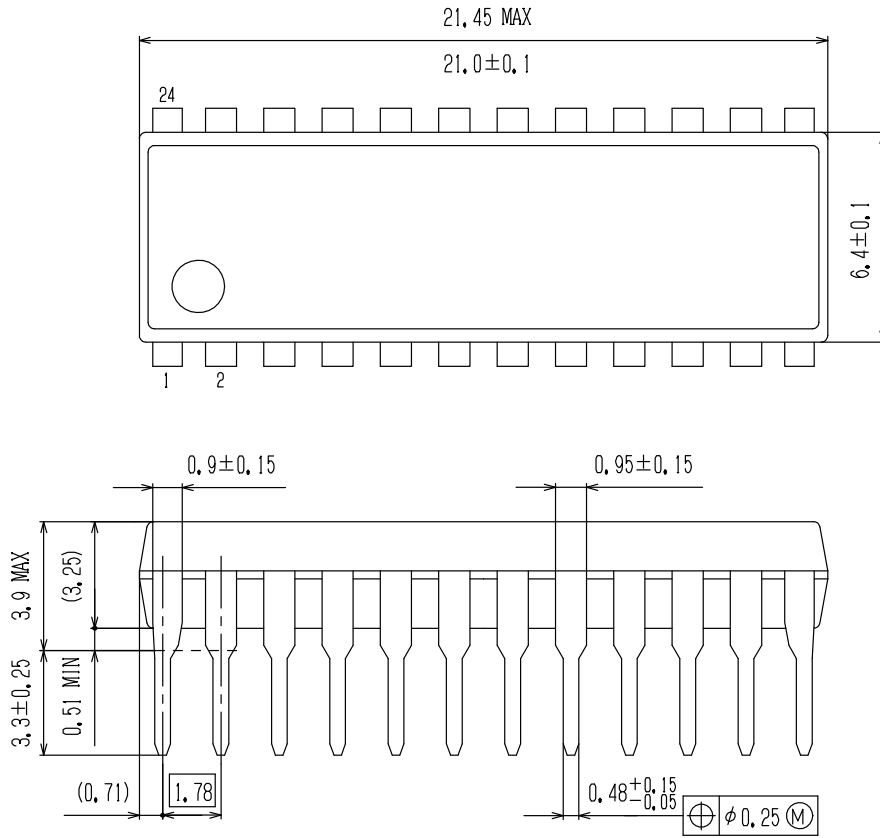
PACKAGE DIMENSIONS

ON Semiconductor®

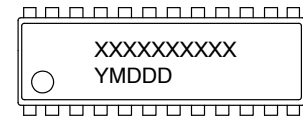


PDIP24 / DIP24S (300 mil)
CASE 646AW
ISSUE A

DATE 16 OCT 2013



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

Y = Year

M = Month

DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

DOCUMENT NUMBER:	98AON65400E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	PDIP24 21X6.4MM, 1.78P / DIP24S (300MIL)	PAGE 1 OF 2

